

# Molding Type Module IGBT 2-in 1-Package, 1200 V, 75 A



PRIMARY CHARACTERISTICS					
$V_{CES}$	1200 V				
$I_C$ at $T_C = 80  ^{\circ}C$	75 A				
$V_{CE(on)}$ (typical) at $I_C = 75$ A, $T_J = 25$ °C	1.90 V				
Speed	8 kHz to 30 kHz				
Package	INT-A-PAK				
Circuit configuration	Half bridge				

### **FEATURES**

- High short circuit capability, self limiting to 6 x I
- 10 µs short circuit capability
- V<sub>CE(on)</sub> with positive temperature coefficient
- Low inductance case
- · Fast and soft reverse recovery antiparallel FWD
- Isolated copper baseplate using DCB (Direct Copper Bonding) technology
- Material categorization: for definitions of compliance please see <a href="https://www.vishay.com/doc?99912"><u>www.vishay.com/doc?99912</u></a>

### **TYPICAL APPLICATIONS**

- AC inverter drivers
- · Electronic welders
- Switching mode power supplies

#### DESCRIPTION

Vishay's IGBT power module provides ultra low conduction loss as well as short circuit ruggedness. It is designed for applications such as general inverters and UPS.

<b>ABSOLUTE MAXIMUM RATINGS</b> (T <sub>C</sub> = 25 °C unless otherwise noted)					
PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS	
Collector to emitter voltage	V <sub>CES</sub>		1200	V	
Gate to emitter voltage	$V_{GES}$		± 20	V	
Collector current		T <sub>C</sub> = 25 °C	150		
Collector current	Ic	T <sub>C</sub> = 80 °C	75		
Pulsed collector current	I <sub>CM</sub> <sup>(1)</sup>	t <sub>p</sub> = 1 ms	150	Α	
Diode continuous forward current	I <sub>F</sub>	T <sub>C</sub> = 80 °C	75		
Diode maximum forward current	I <sub>FM</sub> <sup>(1)</sup>	t <sub>p</sub> = 1 ms	150		
Maximum power dissipation	P <sub>D</sub>	T <sub>J</sub> = 150 °C	543	W	
Short circuit withstand time	T <sub>SC</sub>	T <sub>J</sub> = 125 °C	10	μs	
l <sup>2</sup> t-value, diode		$V_R = 0 \text{ V, t} = 10 \text{ ms, T}_J = 125 \text{ °C}$	1050	A <sup>2</sup> s	
RMS isolation voltage	V <sub>ISOL</sub>	f = 50 Hz, t = 1 min	2500	V	
Maximum junction temperature	TJ		+150	°C	

#### Note

<sup>(1)</sup> Repetitive rating: pulse width limited by maximum junction temperature

IGBT ELECTRICAL SPECIFICATIONS (T <sub>C</sub> = 25 °C unless otherwise noted)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Collector to emitter breakdown voltage	V <sub>(BR)CES</sub>	$V_{GE} = 0 \text{ V}, I_{C} = 1.0 \text{ mA}, T_{J} = 25 \text{ °C}$	1200	-	-	
Collector to emitter voltage	V	$V_{GE} = 15 \text{ V}, I_{C} = 75 \text{ A}, T_{J} = 25 ^{\circ}\text{C}$	-	1.9	2.35	V
Collector to enlitter voltage	V <sub>CE(on)</sub>	V <sub>GE</sub> = 15 V, I <sub>C</sub> = 75 A, T <sub>J</sub> = 125 °C	-	2.1	-	V
Gate to emitter threshold voltage	V <sub>GE(th)</sub>	$V_{CE} = V_{GE}$ , $I_C = 3.0$ mA, $T_J = 25$ °C	5.0	6.2	7.0	
Collector cut-off current	I <sub>CES</sub>	$V_{CE} = V_{CES}$ , $V_{GE} = 0$ V, $T_{J} = 25$ °C	-	-	5.0	mA
Gate to emitter leakage current	I <sub>GES</sub>	$V_{GE} = V_{GES}$ , $V_{CE} = 0$ V, $T_{J} = 25$ °C	-	-	400	nA

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SWITCHING CHARACTERISTICS						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Turn-on delay time	t <sub>d(on)</sub>		-	305	-	ns mJ
Rise time	t <sub>r</sub>		-	67	-	
Turn-off delay time	t <sub>d(off)</sub>	$V_{CC} = 600 \text{ V}, I_{C} = 75 \text{ A}, R_{g} = 10 \Omega,$	-	328	-	
Fall time	t <sub>f</sub>	$V_{GE} = \pm 15 \text{ V}, T_{J} = 25 \text{ °C}$	-	187	-	
Turn-on switching loss	E <sub>on</sub>		-	6.74	-	
Turn-off switching loss	E <sub>off</sub>		-	4.25	-	
Turn-on delay time	t <sub>d(on)</sub>		-	311	-	ns ns
Rise time	t <sub>r</sub>		-	67	-	
Turn-off delay time	t <sub>d(off)</sub>	$V_{CC} = 600 \text{ V}, I_{C} = 75 \text{ A}, R_{g} = 10 \Omega,$	-	347	-	
Fall time	t <sub>f</sub>	V <sub>GE</sub> = ± 15 V, T <sub>J</sub> = 125 °C	-	337	-	
Turn-on switching loss	E <sub>on</sub>		-	9.75	-	m l
Turn-off switching loss	E <sub>off</sub>		-	7.05	-	- mJ
Input capacitance	C <sub>ies</sub>		-	5.52	-	
Output capacitance	C <sub>oes</sub>	$V_{GE} = 0 \text{ V}, V_{CE} = 25 \text{ V}, f = 1.0 \text{ MHz}, $ $T_{.1} = 25 \text{ °C}$	-	0.40	-	nF
Reverse transfer capacitance	C <sub>res</sub>	- 1,1 - 23 · 3	-	0.26	-	
SC data	I <sub>SC</sub>	$t_{S} \le 10 \ \mu s, \ V_{GE} = 15 \ V, \ T_{J} = 125 \ ^{\circ}C, \ V_{CC} = 900 \ V, \ V_{CEM} \le 1200 \ V$	-	350	-	Α
Internal gate resistance	R <sub>GINT</sub>		-	3	-	Ω
Stray inductance	L <sub>CE</sub>		-	-	30	nΗ
Module lead resistance, terminal to chip	R <sub>CC'+EE'</sub>		-	0.75	-	mΩ

<b>DIODE ELECTRICAL SPECIFICATIONS</b> (T <sub>C</sub> = 25 °C unless otherwise noted)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS
Forward voltage	V <sub>F</sub>	I <sub>F</sub> = 75 A	T <sub>J</sub> = 25 °C	-	1.78	2.18	V
Torward voltage			T <sub>J</sub> = 125 °C	-	1.85	-	
Poverse receivery charge	Q <sub>rr</sub>	Q <sub>rr</sub>	T <sub>J</sub> = 25 °C	-	4.0	-	
Reverse recovery charge			T <sub>J</sub> = 125 °C	-	9.3	-	μC
Dool voyage vocayan ayarant	I <sub>rr</sub>	$I_{rr} = \begin{cases} I_F = 75 \text{ A, } V_R = 600 \text{ V,} \\ dI_F/dt = 1300 \text{ A/}\mu\text{s} \\ V_{GE} = -15 \text{ V} \end{cases}$	T <sub>J</sub> = 25 °C	-	55	-	^
Peak reverse recovery current			T <sub>J</sub> = 125 °C	-	73	-	A
Deviates received analysis	E <sub>rec</sub>		T <sub>J</sub> = 25 °C	-	2.98	-	
Reverse recovery energy			T <sub>J</sub> = 125 °C	-	4.46	-	mJ

THERMAL AND MECHANICAL SPECIFICATIONS							
PARAMETER		SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Maximum junction temperature	)	TJ		-	-	150	°C
Storage temperature range		T <sub>Stg</sub>		-40	-	125	°C
Junction to case	IGBT	В		-	-	0.23	
per ½ module	Diode	R <sub>thJC</sub>		-	=.	0.33	K/W
Case to sink (conductive greas	e applied)	R <sub>thCS</sub>		-	0.05	-	
Mounting torque			Power terminal screw: M5		2.5 to 5.0		Nima
			Mounting screw: M6	;	3.0 to 5.0	)	Nm
Weight			Weight of module	-	150	-	g



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# Vishay Semiconductors

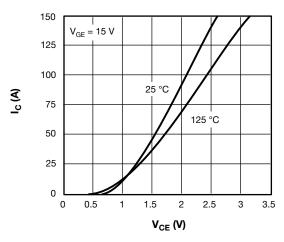


Fig. 1 - IGBT Typical Output Characteristics

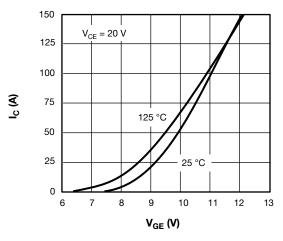


Fig. 2 - IGBT Typical Transfer Characteristics

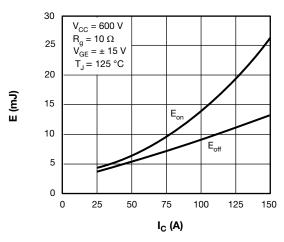


Fig. 3 - IGBT Switching Loss vs. I<sub>C</sub>

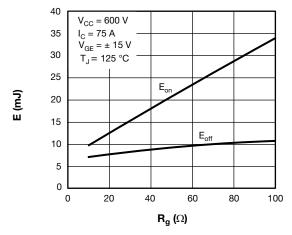


Fig. 4 - IGBT Switching Loss vs. R<sub>q</sub>

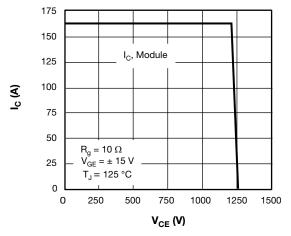


Fig. 5 - RBSOA

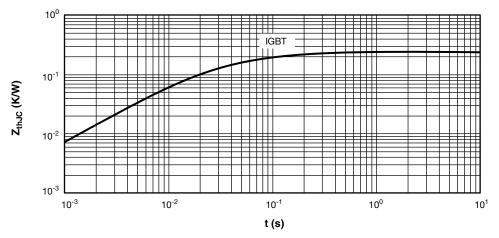


Fig. 6 - IGBT Transient Thermal Impedance

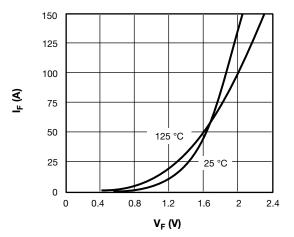


Fig. 7 - Typical Diode Forward Characteristics

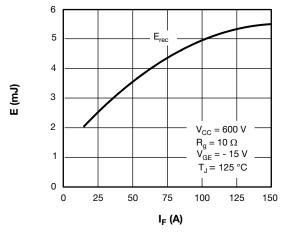


Fig. 8 - Diode Switching Loss vs.  $I_F$ 

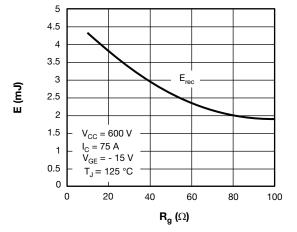


Fig. 9 - Diode Switching Loss vs. Rq

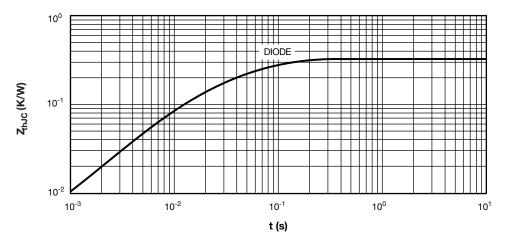
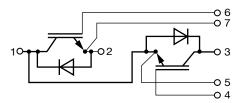


Fig. 10 - Diode Transient Thermal Impedance

### **CIRCUIT CONFIGURATION**

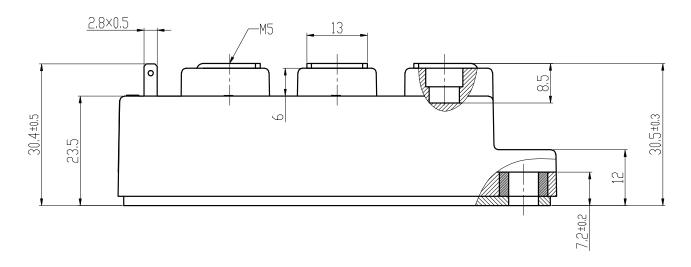


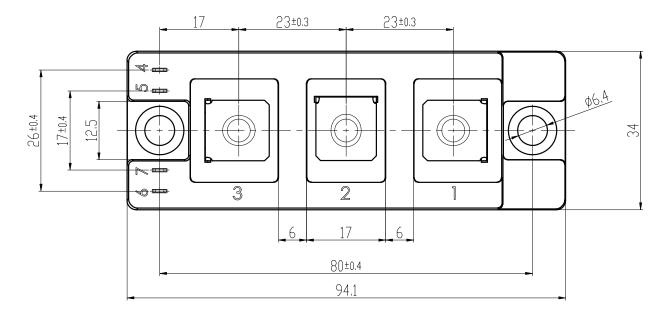
LINKS TO RELATED DOCUMENTS				
Dimensions	www.vishay.com/doc?95524			



### **INT-A-PAK**

### **DIMENSIONS** in millimeters (inches)





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